

Multi-functional Integrated System Technology

## Harsh Environment Sensing



While readily available commercial sensors may be adequate for consumer IoT and smart systems, smart systems for harsh environments involving one or more extremes of temperature, pressure, corrosive liquids, radiation, etc. often require specialized sensors. Some target applications include aerospace, gas turbine, reactor, as well as seawater and in vivo applications.

Founded in 2014, the Multi-functional Integrated System technology (MIST) Center is a research consortium under the auspices of the Industry/ University Cooperative Research Centers program at the National Science Foundation.

Since 2015, the MIST Center has funded \$1.5M across 33 projects conducted by 13 faculty members resulting in 11 publications, 3 patents and 2 doctoral student hired by a member organization.



million dollars of directly funded research

1 IAB-approved journal and conference paper publications

patents issued with the possibility for royalty-free licensing

faculty at three institutions have contributed to this body of work

doctoral student hired by a member organization



Prof. Mark Sheplak's complete sensor package for a flush-mounted, dual-axis differential capacitive wall shear stress sensor.

Prof. HJ Cho's fabricated pseudo-reference

electrode on a flexible substrate for heavy

## **Related Intellectual Property**

- 1. Combined Electrochemical pH/Phosphate Sensor. Provisional Patent No. 62/900,160. Application Date = Sept. 13, 2019. Status = Provisional Filed.
- 2. Low cost disposablemedical sensor fabricated on glass, paper or plastics. Patent No. 16/206,493. US. Application Date = Nov. 30, 2018. Status = Utility Filed
- 3. A Flush-Mount Packaging Method for Micromachined Transducers. Patent No. 10,737,933. US. Application Date = Sept. 13, 2018. Status = Patent Issued Aug. 11, 2020.

## **List of Projects**

- 1. Room Temperature Ultra-fast IR Detectors Using Patterned Graphene Absorbers on MCT (A. Ghosh, D. Chanda). 2021.
- 2. Controlling Infrared Modulation with Thermal Resistances (P. Hopkins). 2020-2021.
- 3. MWIR/LWIR Imaging Fiber Bundle Development (K. Renshaw). 2020.
- 4. High Bandwidth Heat Flux Sensor (M. Sheplak). 2020.
- 5. Conformal Electrochemical Sensors for Heavy Metal Detection (H.J. Cho, W.H. Lee). 2019.
- 6. Flat-Packaged Optical Pressure Sensor for Extreme Temperature Environments (M. Sheplak). 2018-2021.
- 7. Flexible MOS/Polymer Composite Films for Multifunctional Sensing Applications (H.J. Cho). 2018.
- 8. Avalanche Photodiodes for Biological Detectors (J. Campbell). 2018-2019.
- 9. Integrated sensors for environmental monitoring (Y.K. Yoon). 2018-2020.
- 10. AlGaN/GaN High Electron Mobility Transistor (HEMT) Based Sensor for Heart Attack Detection (F. Ren, S. Pearton). 2017.
- 11. Technology Development Towards a MEMS-Based Multi-Hole Probe with Optical Transducers (M. Sheplak). 2017-2020.
- 12. Technology Development for a Dual-Axis Wall Shear Stress Sensor System (M. Sheplak). 2017-2020.
- 13. 5-axis Laser Micromachining Capabilities for Ceramics Manufacturing (M. Sheplak). 2016-2017.
- 14. Thermal Stress Minimization for Harsh Environment Packaging (M. Sheplak, T. Jiang). 2015-2016.
- 15. Laser Micromachining of 3-D Miniature Parts in Harsh Materials (M. Sheplak). 2015.
- 16. Nanowire Gas Sensors (H.J. Cho). 2015-2017.

Publication lists available upon request







